

複合式微波電漿光阻去除機

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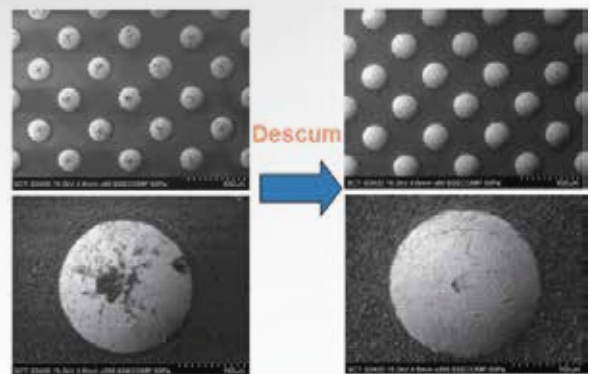
Microwave Plasma Photoresist Removal Equipment

PRST-BMR3010 / BM2R3010



機台特點 Characteristics

1. 適用於8"/12"晶圓
Apply to 8"/12" wafer.
2. 系統可選擇2~6個製程腔
2-6 process chambers selectable.
3. 穩定的傳輸系統
Stable transfer system
4. 全面數位控制系統，具備聯網功能
Fully digital control and SECS/GEM compliant.
5. 三種製程模式選擇：微波、射頻、微波+射頻
3 processes mode: microwave, RF or dual source.
6. 低損傷微波電漿系統
Low damage microwave plasma system.
7. 高密度微波電漿提升電漿處理效率
High density microwave plasma can enhance the processes efficiency.
8. 遠程電漿系統可以降低製程溫度及電漿損傷
Remote plasma system can reduce the processes temperature and the damage of plasma.



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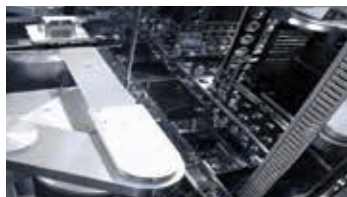
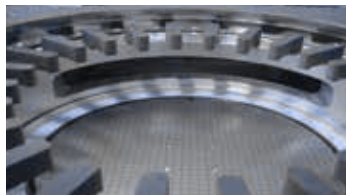
Leading in Thermal and UV Light Processing Equipment

PRST-BMR3010 / BM2R3010 複合式微波電漿光阻去除機

基板尺寸 Substrate size	8" / 12" wafer
腔體數目 Number of chamber	2 ~ 6
傳送機構 Transfer system	4-axis dual arm robot
載入機構 Load port	2 ~ 4 FOUFs
電漿源 Plasma source	Remote microwave (2.45 GHz) RIE mode (bias, 2 MHz) Dual source (Microwave, bias)
射頻電源電力規格 Generator power	2.45 GHz, 3kW (Microwave) 13.56 MHz, 1kW (RIE) (PRST-BMR2010) 2.45 GHz, 3kW (Microwave) 2 MHz, 1kW (RIE) (PRST-BM2R2010)
製程氣體 Process gas	O ₂ 、Ar、N ₂ 、CF ₄ 、Mixture (Max. 7 gas lines)
氣體流量控制 Gas flow control	MFC (±1% of set point) 註：流量設定≥全流量40%，控制精度為±1% of set point，<40%時控制精度為±0.4% of full scale Note: Control accuracy ±1% of set point when flow rate ≥40%, control accuracy ±0.4% of full scale when flow rate <40%
腔體材質 Material of chamber	Aluminum alloy
泵浦規格 Standard pump	Dry pump, pumping speed >500 cfm @60 Hz
製程壓力計 Pressure gauge	Capacitive pressure sensor
製程壓力控制 EQ pressure	50~800 mTorr
控制系統 Control system	19.5 inch TFT panel / PC / Windows 10
載台溫度控制 Stage temperature controller	Thermo-chiller
規範 Compliance	SEMI S2-01, SEMI S8-01, SECS/GEM

Due to C SUN continuing efforts to improve their systems, these specifications are subject to change without notice.
受長期研發需要，本公司保有規格修改之權利，恕不另行通知

DM2023Q2-000-TW



應用 Applications

- 光阻剝除
PR Stripping
- 殘膠去除
Descum
- 聚合物去除
Polymer removal
- 氧化矽/氮化矽/矽蝕刻
SiO_x / SiN_x / Si etching
- 表面清潔及改質
Surface clean & treatment
- 金屬氧化還原
Metal reduction oxidation

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